

July 1998

## NM27C240 4 194 304-Bit (256k x 10

# 4,194,304-Bit (256k x 16) High Performance CMOS EPROM

## **General Description**

The NM27C240 is a high performance Electrically Programmable UV erasable ROM (EPROM). It contains 4,194,304 bits configured as 256k x 16 bits. It is offered in both erasable versions for prototyping and early production applications as well as non-erasable, plastic packaged versions that are ideal for high volume and automated assembly applications.

The NM27C240 operates from a single 5V  $\pm 10\%$  supply in the read mode.

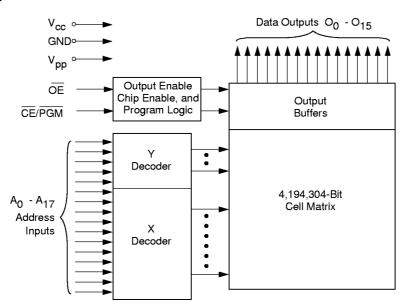
The NM27C240 is offered in both DIP and surface mount packages. The DIP package is a 40-pin dual-in-line ceramic with a quartz window to allow erasing. The surface mount package is a 44-pin PLCC that is offered in OTP.

This EPROM is manufactured using Fairchild's proprietary AMG™ EPROM technology for an excellent combination of speed and economy while providing excellent reliability.

### **Features**

- High performance CMOS
  - 100 ns access time
- Fast turn-off for microprocessor compatibility
- Simplified upgrade path
  - —V<sub>PP</sub> and PGM are "Don't Care" during normal read operation
- Compatible with 27240 and 27C240 EPROMs
- JEDEC standard pin configuration
  - -40-pin DIP package
  - -44-pin PLCC package
- Manufacturer's identification code
- Fast programming algorithm

## **Block Diagram**



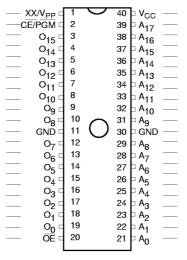
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## **Connection Diagrams**

### **DIP PIN CONFIGURATIONS**

DIP						
NM27C240						
1	$\overline{}$	40				



XX/PGM PGM A  NC A16 A  A15 A15 A  A14 A14 A  A13 A13 A  A12 A12 A  A11 A11 A  A10 A10 A  A9 A9 A9  GND GND GI  A8 A8 A8  A7 A7  A6 A6  A5 A5  A4 A4 A4	27C210	27C220	27C280
M3   M3   M	V <sub>CC</sub> XX/PGM NC A15 A14 A13 A12 A11 A10 A9 GND A8 A7 A6 A5 A4 A3	V <sub>CC</sub> PGM A16 A15 A14 A13 A12 A11 A10 A9 GND A8 A7 A6 A5 A4 A3	V <sub>CC</sub> A <sub>17</sub> A <sub>16</sub> A <sub>15</sub> A <sub>14</sub> A <sub>13</sub> A <sub>12</sub> A <sub>11</sub> A <sub>10</sub> A <sub>9</sub> GND A <sub>8</sub> A <sub>7</sub> A <sub>6</sub> A <sub>5</sub> A <sub>4</sub> A <sub>3</sub>
$\begin{bmatrix} A_2 & A_2 & A_1 \\ A_1 & A_1 & A_1 \end{bmatrix}$	A <sub>2</sub> A <sub>1</sub>	A <sub>2</sub> A <sub>1</sub>	A <sub>2</sub> A <sub>1</sub> A <sub>0</sub>

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Note: Compatible EPROM pin configurations are shown in the blocks adjacent to the NM27C240 pins.

## **Commercial Temperature Range**

 $(0^{\circ}\text{C to } +70^{\circ}\text{C}) \text{ V}_{\text{CC}} = 5\text{V} \pm 10\%$ 

Parameter/Order Number	Access Time (ns)
NM27C240 Q, V, N 100	100
NM27C240 Q, V, N 120	120
NM27C240 Q, V, N 150	150

**Note:** Surface mount PLCC package available for commercial and extended temperature ranges only.

Package types: NM27C240 Q, V, N XXX

Q = Quartz-Windowed Ceramic DIP Package

V = PLCC Package

N = Plastic DIP Package

- All packages conform to JEDEC standard.
- All versions are guaranteed to function in slower applications.

### **Pin Names**

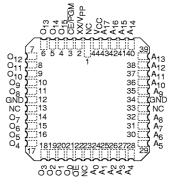
A0-A15	Addresses
CE/PGM	Chip Enable/Program
ŌE	Output Enable
O0-O15	Outputs
XX	Don't Care (During Read)
NC	No Connect

## **Extended Temperature Range**

 $(-40^{\circ} \text{ to } +85^{\circ}\text{C}) \text{ V}_{CC} = 5\text{V} \pm 10\%$ 

Parameter/Order Number	Access Time (ns)
NM27C240 QE, VE, NE 120	120
NM27C240 QE, VE, NE 150	150

### **PLCC Pin Configuration**



**Top View** 

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## **Absolute Maximum Ratings** (Note 1)

Storage Temperature -65°C to +150°C

All Input Voltages except A9 with

Respect to Ground (Note 10) -0.6V to +7V

 $V_{\mbox{\footnotesize PP}}$  and A9 with

Respect to Ground -0.6V to +14V

V<sub>CC</sub> Supply Voltage with

Respect to Ground -0.6V to +7V

ESD Protection >2000V

All Output Voltages with Respect

to Ground (Note 10) V<sub>CC</sub> + 1.0V to GND - 0.6V

## **Operating Range**

Range	Temperature	V <sub>cc</sub>	Tolerance	
Commercial	0°C to +70°C	+5V	±10%	
Industrial	-40V°C to +85°C	+5V	±10%	

## **DC Read Characteristics** Over Operating Range with $V_{PP} = V_{CC}$

Symbol	Parameter	Conditions		Min	Max	Units
V <sub>IL</sub>	Input Low Level			-0.5	0.8	V
V <sub>IH</sub>	Input High Level			2.0	V <sub>CC</sub> +1	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA			0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -2.5 mA		3.5		V
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current (CMOS)	$\overline{CE} = V_{CC} \pm 0.3V$			100	μΑ
I <sub>SB2</sub>	V <sub>CC</sub> Standby Current (TTL)	CE = V <sub>IH</sub>			1	mA
I <sub>cc</sub>	V <sub>CC</sub> Active Current	$\overline{CE} = \overline{OE} = V_{IL}$ , I/O = 0 mA	f=5 MHz		40	mA
I <sub>PP</sub>	V <sub>PP</sub> Supply Current	$V_{PP} = V_{CC}$			10	μΑ
ILI	Input Load Current	V <sub>IN</sub> = 5.5V or GND		-1	1	μΑ
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 5.5V or GND		-10	10	μΑ

## AC Read Characteristics Over Operating Range with $V_{PP} = V_{CC}$

Symbol	Parameter	1	100 120		20	150		Units
		Min	Max	Min	Max	Min	Max	
t <sub>ACC</sub>	Address to Output Delay		100		120		150	ns
t <sub>CE</sub>	CE to Output Delay		100		120		150	
t <sub>OE</sub>	OE to Output Delay		50		50		50	
t <sub>DF</sub> (Note 2)	Output Disable to Output Float		35		35		45	
t <sub>OH</sub> (Note 2)	Output Hold from Addresses CE or OE , Whichever Occurred First	0		0		0		

## **Capacitance** $T_A = +25$ °C, f = 1 MHz (Note 2)

Symbol	Parameter	Conditions	Тур	Max	Units
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	12	20	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	13	20	pF

## **AC Test Conditions**

Output Load 1 TTL Gate and  $C_L = 100 \text{ pF}$  (Note 8)

Input Rise and Fall Times ≤5 ns

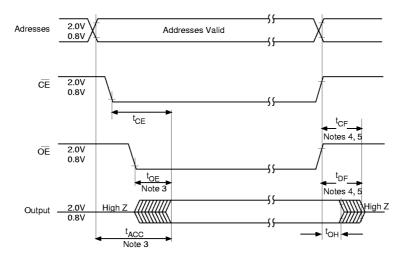
Input Pulse Levels 0.45V to 2.4V

Timing Measurement Reference Level

 Inputs
 0.8V and 2V

 Outputs
 0.8V and 2V

## AC Waveforms (Notes 6, 7) (Note 9)



**Note 1:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: This parameter is only sampled and is not 100% tested.

 $\textbf{Note 3:} \quad \overline{\text{OE}} \text{ may be delayed up to } t_{\text{ACC}} - t_{\text{OE}} \text{ after the falling edge of } \overline{\text{CE}} \text{ without impacting } t_{\text{ACC}}.$ 

Note 4: The  $t_{OF}$  and  $t_{CF}$  compare level is determined as follows: High to TRI-STATE<sup>®</sup>, the measured  $V_{OH1}$  (DC) - 0.10V; Low to TRI-STATE, the measured  $V_{OL1}$  (DC) + 0.10V.

Note 5: TRI-STATE may be attained using OE or CE

Note 6: The power switching characteristics of EPROMs require careful device decoupling. It is recommended that at least a 0.1 μF ceramic capacitor be used on every device between V<sub>CC</sub> and GND.

Note 7: The outputs must be restricted to  $V_{CC}$  + 1.0V to avoid latch-up and device damage.

Note 8: 1 TTL Gate:  $I_{OL}$  = 1.6 mA,  $I_{OH}$  = -400  $\mu$ A.  $C_L$ : 100 pF includes fixture capacitance.

Note 9:  $V_{PP}$  may be connected to  $V_{CC}$  except during programming.

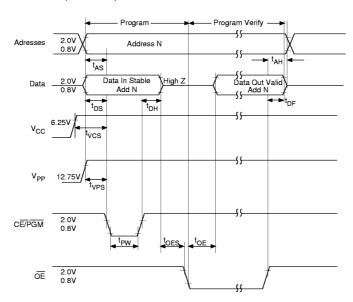
Note 10: Inputs and outputs can undershoot to -2.0V for 20 ns Max.

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## DC Electrical Characteristics (Notes 11, 12, 13, 14)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t <sub>AS</sub>	Address Setup Time		1			μs
t <sub>OES</sub>	OE Setup Time		1			μs
t <sub>DS</sub>	Data Setup Time		1		2.4	μs
t <sub>VPS</sub>	V <sub>PP</sub> Setup Time		1			μs
t <sub>vcs</sub>	V <sub>CC</sub> Setup Time		1			μs
t <sub>AH</sub>	Address Hold Time		0			μs
t <sub>DH</sub>	Data Hold Time		1			μs
t <sub>DF</sub>	Output Enable to Output Float Delay	CE = V <sub>IL</sub>	0		60	ns
t <sub>PW</sub>	Program Pulse Width		45	50	105	μs
t <sub>OE</sub>	Data Valid from OE	CE = V <sub>IL</sub>			100	ns
I <sub>PP</sub>	V <sub>PP</sub> Supply Current during Programming Pulse	$\overline{CE} = V_{IL}, \overline{PGM} = V_{IL}$			30	mA
I <sub>cc</sub>	V <sub>CC</sub> Supply Current				30	mA
T <sub>A</sub>	Temperature Ambient		20	25	30	°C
V <sub>CC</sub>	Power Supply Voltage		6.25	6.5	6.75	V
$V_{PP}$	Programming Supply Voltage		12.5	12.75	13.0	V
t <sub>FR</sub>	Input Rise, Fall Time		5			ns
V <sub>IL</sub>	Input Low Voltage			0.0	0.45	V
V <sub>IH</sub>	Input High Voltage		2.4	4.0		V
t <sub>IN</sub>	Input Timing Reference Voltage		0.8		2.0	V
t <sub>out</sub>	Output Timing Reference Voltage		0.8		2.0	V

## **Programming Waveforms** (Note 13)



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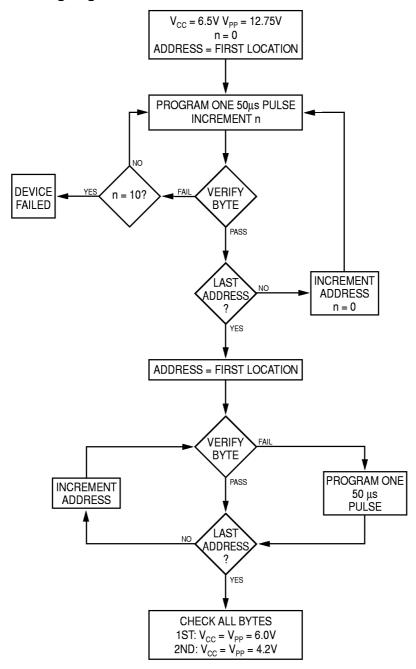
Note 11: Fairchild's standard product warranty applies only to devices programmed to specifications described herein.

Note 12: V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>. The EPROM must not be inserted into or removed from a board with voltage applied to V<sub>PP</sub> or V<sub>CC</sub>.

Note 13: The maximum absolute allowable voltage which may be applied to the V<sub>PP</sub> pin during programming is 14V. Care must be taken when switching the V<sub>PP</sub> supply to prevent any overshoot from exceeding this 14V maximum specification. At least a 0.1 µF capacitor is required across V<sub>PP</sub>, V<sub>CC</sub> to GND to suppress spurious voltage transients which may damage the device.

Note 14: During power up the CE/PGM pin must be brought high (≥V<sub>IH</sub>) either coincident with or before power is applied to V<sub>PP</sub>.

## **Turbo Programming Algorithm Flow Chart**



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Note: The standard National Semiconductor algorithm may also be used but it will have longer programming time.

FIGURE 1.

## Functional Description DEVICE OPERATION

The six modes of operation of the EPROM are listed in Table 1. It should be noted that all inputs for the six modes are at TTL levels. The power supplies required are  $V_{\rm CC}$  and  $V_{\rm PP}.$   $V_{\rm CC}$  power supply must be at 12.75V during the three programming modes, and must be at 5V in the other three modes. The  $V_{\rm CC}$  power supply must be at 6.5V during the three programming modes, and at 5V in the other three modes.

### Mode Selection

The modes of operation of the NM27C240 are listed in Table 1. A single 5V power supply is required in the read mode. All inputs are TTL levels except for  $V_{PP}$  and A9 for device signature.

**TABLE 1. Modes Selection** 

	Pins					
Mode	CE/ PGM	OE	V <sub>PP</sub>	V <sub>cc</sub>	Outputs	
Read	V <sub>IL</sub>	V <sub>IL</sub>	Х	5.0V	D <sub>OUT</sub>	
Output Disable	Х	V <sub>IH</sub>	Х	5.0V	High Z	
Standby	V <sub>IH</sub>	Х	Х	5.0V	High Z	
Programming	V <sub>IL</sub>	V <sub>IH</sub>	12.75V	6.25V	D <sub>IN</sub>	
Program Verify	V <sub>IL</sub>	V <sub>IL</sub>	12.75V	6.25V	D <sub>OUT</sub>	
Program Inhibit	V <sub>IH</sub>	Х	12.75V	6.25V	High Z	

Note 15: X can be  $V_{IL}$  or  $V_{IH}$ .

### **Read Mode**

The EPROM has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of the device selection. Assuming that the addresses are stable, address access time ( $t_{ACC}$ ) is equal to the delay from CE to output ( $t_{CE}$ ). Data is available at the outputs  $t_{OE}$  after falling edge of OE, assuming that CE has been low and addresses have been stable for at least  $t_{ACC}$  -  $t_{OE}$ .

### Standby Mode

The EPROM standby mode reduces the active power dissipation by over 99%, from 165 mW to 0.55 mW. The EPROM is placed in the standby mode by applying a CMOS high signal to the CE input. When in standby mode, the outputs are in a high impedance state, independent of the OE input.

### **Output Disable**

The EPROM is placed in output disable by applying a TTL high signal to the OE input. When in output disable all circuitry is enabled, except the outputs are in a high impedance state (TRI-STATE).

### **Output OR-Tying**

Because the EPROM is usually used in larger memory arrays, Fairchild has provided a 2-line control function that accommo-

dates this use of multiple connections. The 2-line control function allows for:

- 1. the lowest possible memory power dissipation, and
- the complete assurance that output bus contention will not occur.

To most efficiently use these two control lines, it is recommended that  $\overline{CE}$  be decoded and used as the primary device selecting function, while  $\overline{OE}$  be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low power standby modes and that the output pins are active only when data is desired from a particular memory device.

### **Programming**

**CAUTION:** Exceeding 14V on the  $V_{PP}$  or A9 pin will damage the EPROM.

Initially, and after erasure, all bits of the EPROM are in the "1's" state. Data is introduced by selectively programming "0's" into the desired bit locations. Although only "0's" will be programmed, both "1's" and "0's" can be presented in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure.

The EPROM is in the programming mode when the  $V_{PP}$  power supply is at 12.75V and  $\overline{OE}$  is at  $V_{IH}$ . It is required that at least a 0.1  $\mu$ F capacitor be placed across  $V_{PP}$ ,  $V_{CC}$  to ground to suppress spurious voltage transients which may damage the device. The data to be programmed is applied 16 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.

When the address and data <u>are\_stable</u>, and active low, TTL program pulse is applied to the PGM input. A program pulse must be applied at each address location to be programmed. The EPROM is programmed with the Turbo Programming Algorithm shown in Figure 1. Each Address is programmed with a series of 50 µs pulses until it verifies good, up to a maximum of 10 pulses. Most memory cells will program with a single 50 µs pulse. (The standard National Semiconductor algorithm may also be used but it will have longer programming time.)

The EPROM must not be programmed with a DC signal applied to the PGM input.

Programming multiple EPROM in parallel with the same data can be easily accomplished due to the simplicity of the programming requirements. Like inputs of the parallel EPROM may be connected together when they are programmed with the same data. A low level TTL pulse applied to the PGM input programs the paralleled EPROM.

### Program Inhibit

Programming multiple EPROM's in parallel with different data is also easily accomplished. Except for  $\overline{CE}$  all like inputs (including  $\overline{OE}$  and  $\overline{PGM}$ ) of the parallel EPROM may be common. A TTL low level program pulse applied to an EPROM's PGM input with  $\overline{CE}$  at  $\overline{V_{IL}}$  and  $\overline{V_{PP}}$  at 12.75V will program that EPROM. A TTL high level  $\overline{CE}$  input inhibits the other EPROM's from being programmed.

### **Program Verify**

A verify should be performed on the programmed bits to determine whether they were correctly programmed. The verify may be performed with  $V_{\rm PP}$  at 12.75V.  $V_{\rm PP}$  must be at  $V_{\rm CC},$  except during programming and program verify.

## Functional Description (Continued)

### **After Programming**

Opaque labels should be placed over the EPROM window to prevent unintentional erasure. Covering the window will also prevent temporary functional failure due to the generation of photo currents.

### Manufacturer's Identification Code

The EPROM has a manufacturer's identification code to aid in programming. When the device is inserted in an EPROM programmer socket, the programmer reads the code and then automatically calls up the specific programming algorithm for the part. This automatic programming control is only possible with programmers which have the capability of reading the code.

The manufacturer's identification code, shown in Table 2, specifically identifies the manufacturer and device type. The code for the NM27C240 is "8FEE", where "8F" designates that it is made by Fairchild Semiconductor, and "EE" designates a 4 Megabit (256k  $\times$  16) part.

The code is accessed by applying 12V  $\pm 0.5\%$  to address pin A9. Addresses A1–A8, A10–A15, and all control pins are held at V<sub>IL</sub>. Address pin A0 is held at V<sub>IL</sub> for the manufacturer's code, and held at V<sub>IH</sub> for the device code. The code is read on the lower eight data pins, O0–O7. Proper code access is only guaranteed at 25°C  $\pm 5$ °C.

### **Erasure Characteristics**

The erasure characteristics of the device are such that erasure begins to occur when exposed to light with wavelengths shorter than approximately 4000 Angstroms (Å). It should be noted that sunlight and certain types of fluorescent lamps have wavelengths in the 3000Å–4000Å range.

The recommended erasure procedure for the EPROM is exposure to short wave ultraviolet light which has a wavelength of

2537Å. The integrated dose (i.e., UV intensity x exposure time) for erasure should be minimum of 15W-sec/cm<sup>2</sup>.

The EPROM should be placed within 1 inch of the lamp tubes during erasure. Some lamps have a filter on their tubes which should be removed before erasure.

An erasure system should be calibrated periodically. The distance from lamp to device should be maintained at one inch. The erasure time increases as the square of the distance from the lamp (if distance is doubled the erasure time increases by factor of 4). Lamps lose intensity as they age. When a lamp is changed, the distance has changed, or the lamp has aged, the system should be checked to make sure full erasure is occurring. Incomplete erasure will cause symptoms that can be misleading. Programmers, components, and even system designs have been erroneously suspected when incomplete erasure was the problem.

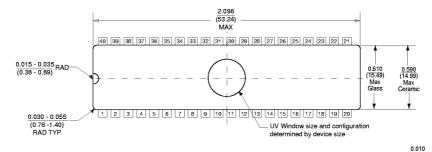
### **System Consideration**

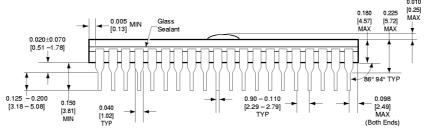
The power switching characteristics of EPROMs require careful decoupling of the devices. The supply current,  $I_{\text{CC}}$ , has three segments that are of interest to the system designer: the standby current level, the active current level, and the transient current peaks that are produced by voltage transitions on input pins. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. The associated  $\rm V_{\rm CC}$ transient voltage peaks can be suppressed by properly selected decoupling capacitors. It is recommended that at least a 0.1  $\mu$ F ceramic capacitor be used on every device between  $V_{\rm CC}$  and GND. This should be a high frequency capacitor of low inherent inductance. In addition, at least a 4.7 μF bulk electrolytic capacitor should be used between V<sub>CC</sub> and GND for each eight devices. The bulk capacitor should be located near where the power supply is connected to the array. The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of the PC board traces.

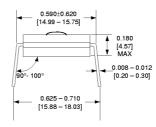
TABLE 2. Manufacturer's Identification Code

Pins	A0 (21)	A9 (31)	O7 (12)	O6 (13)	O5 (14)	O4 (15)	O3 (16)	O2 (17)	O1 (18)	O0 (19)	Hex Data
Manufacturer Code	V <sub>IL</sub>	12V	1	0	0	0	1	1	1	1	8F
Device Code	V <sub>IH</sub>	12V	1	1	1	0	1	1	1	0	EE

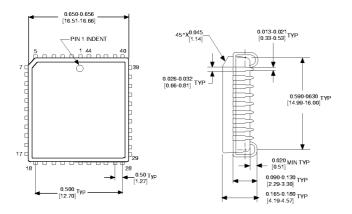
## Physical Dimensions inches (millimeters) unless otherwise noted

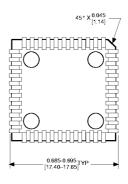






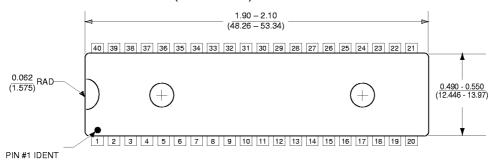
## 40-Lead Ceramic Dual-In-Line Package (Q) Order Number NM27C240Qxxx Package Number J40BQ

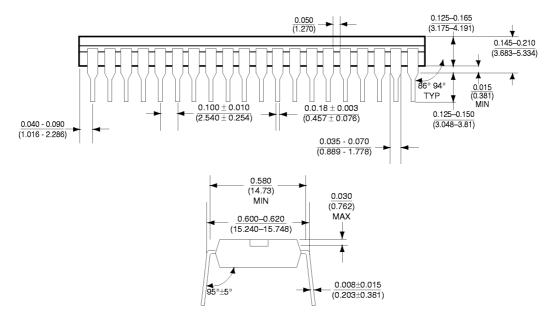




44-Lead Plastic Chip Carrier (V) Order Number NM27C240Vxxx Package Number V44A

## Physical Dimensions inches (millimeters) unless otherwise noted





40-Lead Plastic Molded Dual-In-Line (N)
Order Number NM27C240Nxxx

## Life Support Policy

Fairchild's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of Fairchild Semiconductor Corporation. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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